

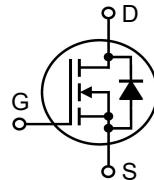
IXYS

**X3-Class HiPerFET™
Power MOSFET**

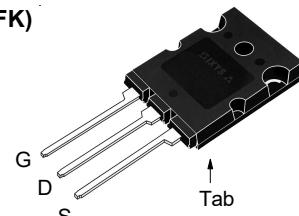
**IXFK300N20X3
IXFX300N20X3**

**V_{DSS} = 200V
I_{D25} = 300A
R_{DS(on)} ≤ 4mΩ**

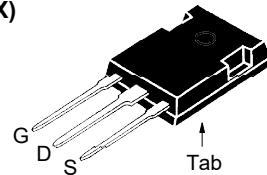
N-Channel Enhancement Mode
Avalanche Rated



**TO-264K
(IXFK)**



**PLUS247
(IXFX)**



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 150°C	200	V
V _{DGR}	T _J = 25°C to 150°C, R _{GS} = 1MΩ	200	V
V _{GSS}	Continuous	±20	V
V _{GSM}	Transient	±30	V
I _{D25}	T _C = 25°C (Chip Capability)	300	A
I _{L(RMS)}	External Lead Current Limit	160	A
I _{DM}	T _C = 25°C, Pulse Width Limited by T _{JM}	700	A
I _A	T _C = 25°C	150	A
E _{AS}	T _C = 25°C	3.5	J
dv/dt	I _S ≤ I _{DM} , V _{DD} ≤ V _{DSS} , T _J ≤ 150°C	50	V/ns
P _D	T _C = 25°C	1250	W
T _J		-55 ... +150	°C
T _{JM}		150	°C
T _{stg}		-55 ... +150	°C
T _L	Maximum Lead Temperature for Soldering 1.6 mm (0.062 in.) from Case for 10s	300	°C
M _d	Mounting Torque (TO-264K)	1.13/10	Nm/lb.in
F _c	Mounting Force (PLUS247)	20..120 / 4.5..27	N/lb
Weight	TO-264K PLUS247	10 6	g

Symbol	Test Conditions (T _J = 25°C, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 3mA	200		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 8mA	2.5		4.5 V
I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±200 nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0V T _J = 125°C			25 μA 1.5 mA
R _{DS(on)}	V _{GS} = 10V, I _D = 0.5 • I _{D25} , Note 1			4 mΩ

Features

- International Standard Packages
- Low R_{DS(ON)} and Q_G
- Avalanche Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls



IXFK300N20X3
IXFX300N20X3

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 60\text{A}$, Note 1	80	135	S
R_{GI}	Gate Input Resistance		1.8	Ω
C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	23.8 4.0 3.2	nF nF pF	
C_{oss}				
C_{rss}				
Effective Output Capacitance				
$C_{o(er)}$	Energy related	$V_{GS} = 0\text{V}$	1640	pF
$C_{o(tr)}$	Time related	$V_{DS} = 0.8 \cdot V_{DSS}$	5640	pF
$t_{d(on)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ $R_G = 1\Omega$ (External)	44	ns	
t_r		43	ns	
$t_{d(off)}$		184	ns	
t_f		13	ns	
$Q_{g(on)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$	375	nC	
Q_{gs}		117	nC	
Q_{gd}		94	nC	
R_{thJC}			0.10 $^\circ\text{C}/\text{W}$	
R_{thCS}		0.15	$^\circ\text{C}/\text{W}$	

Source-Drain Diode

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
I_s	$V_{GS} = 0\text{V}$		300	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}		1200	A
V_{SD}	$I_F = 100\text{A}$, $V_{GS} = 0\text{V}$, Note 1		1.4	V
t_{rr}	$I_F = 150\text{A}$, $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$	172 1.1 12.8	ns μC A	
Q_{RM}				
I_{RM}				

Note 1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.

Littelfuse reserves the right to change limits, test conditions, and dimensions.

LFMOSFETs and IGBTs are covered
by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065B1 6,683,344 6,727,585 7,005,734B2 7,157,338B2
4,860,072 5,017,508 5,063,307 5,381,025 6,259,123B1 6,534,343 6,710,405B2 6,759,692 7,063,975B2
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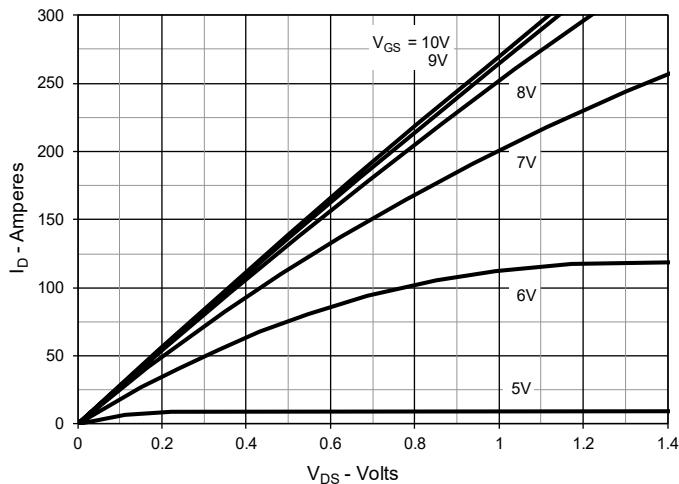
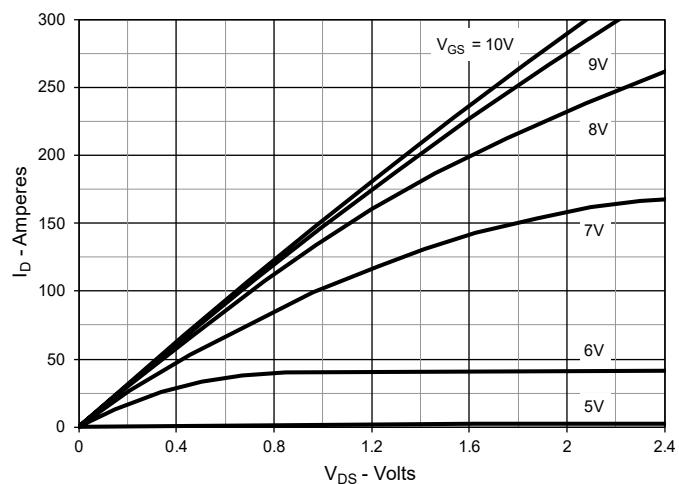
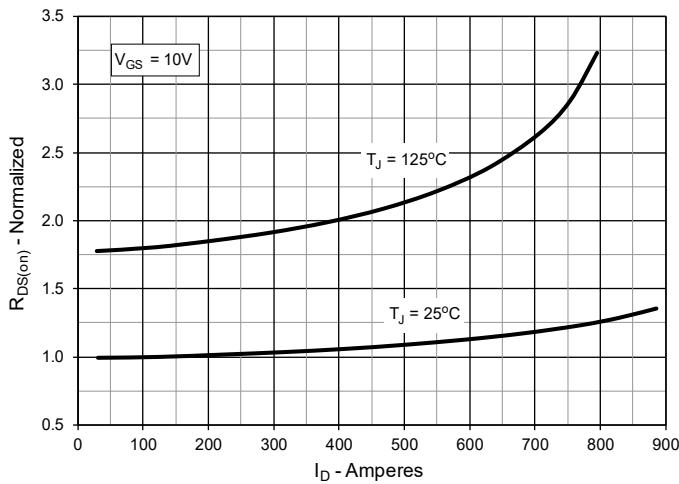
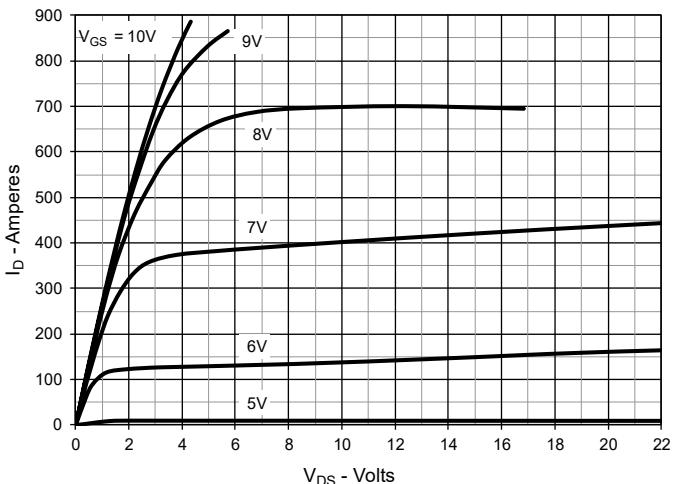
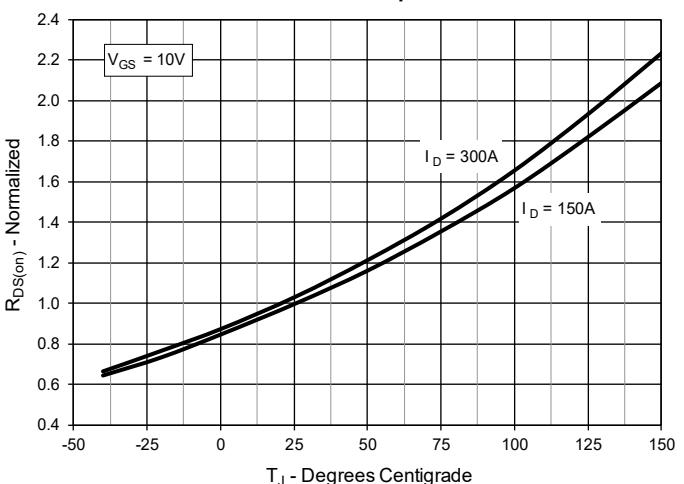
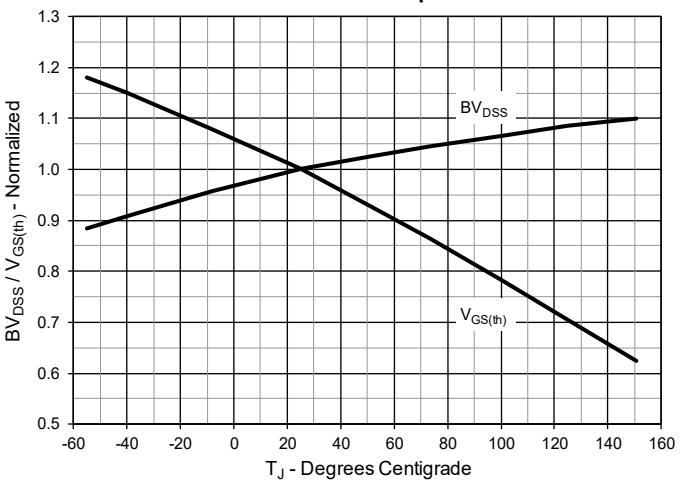
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 150\text{A}$ Value vs. Drain Current

Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 150\text{A}$ Value vs. Junction Temperature

Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature


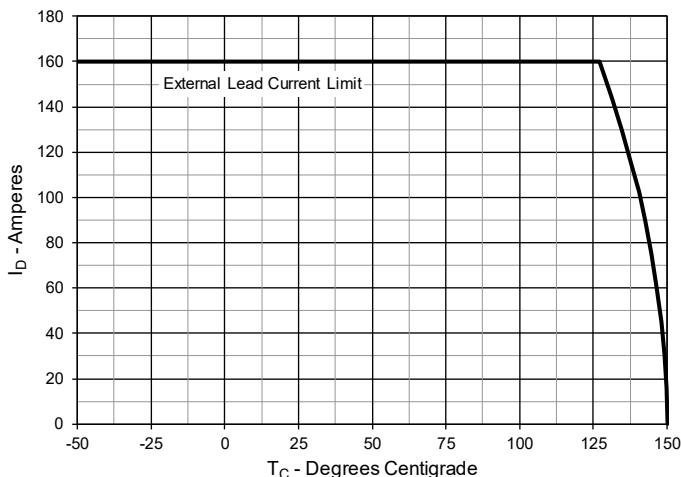
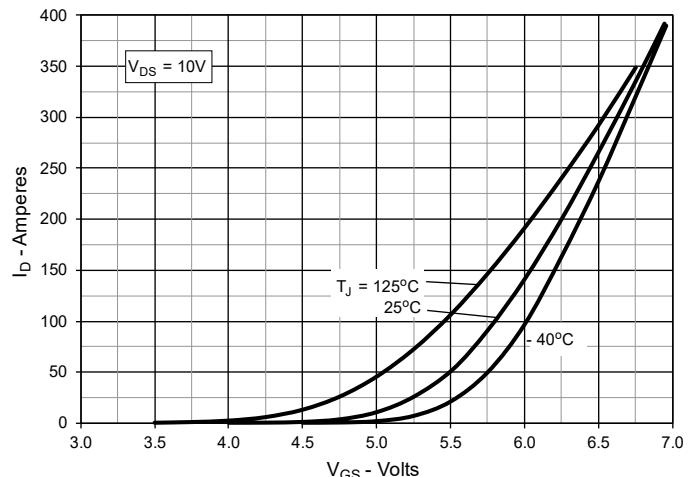
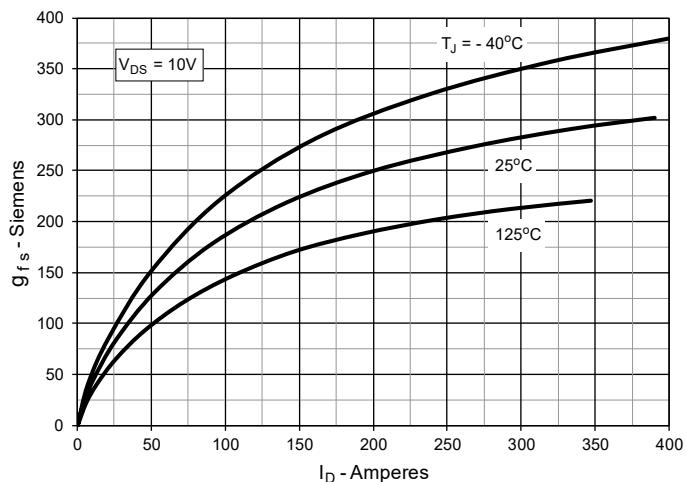
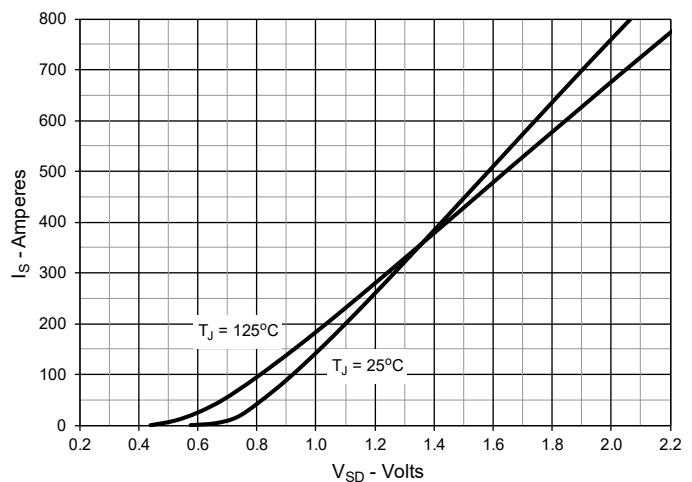
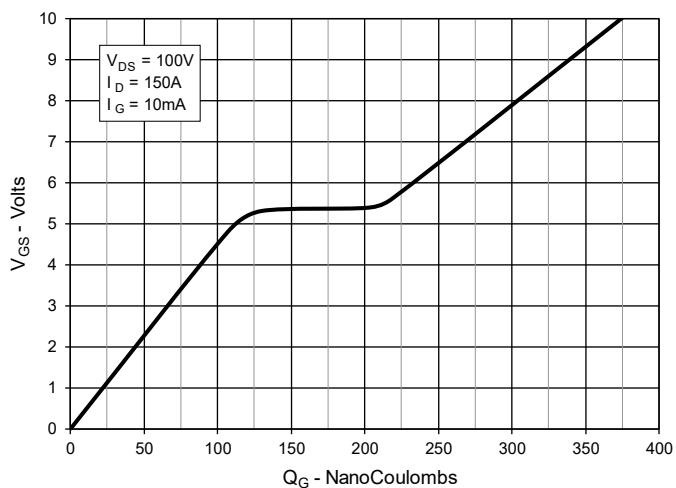
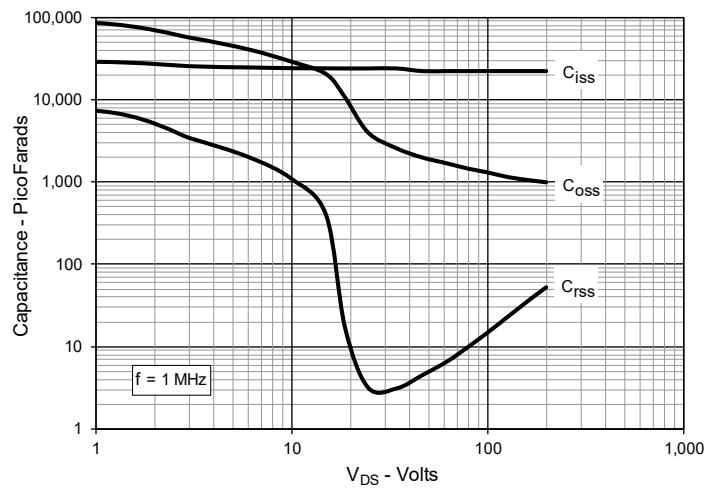
Fig. 7. Maximum Drain Current vs. Case Temperature

Fig. 8. Input Admittance

Fig. 9. Transconductance

Fig. 10. Forward Voltage Drop of Intrinsic Diode

Fig. 11. Gate Charge

Fig. 12. Capacitance


Fig. 13. Output Capacitance Stored Energy

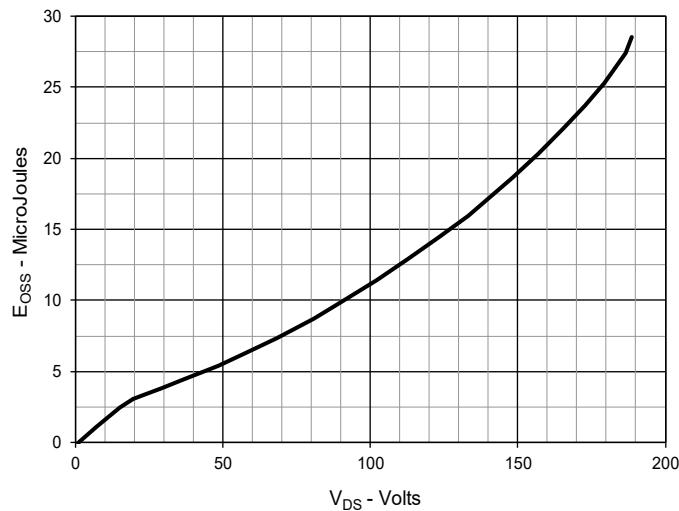


Fig. 14. Forward-Bias Safe Operating Area

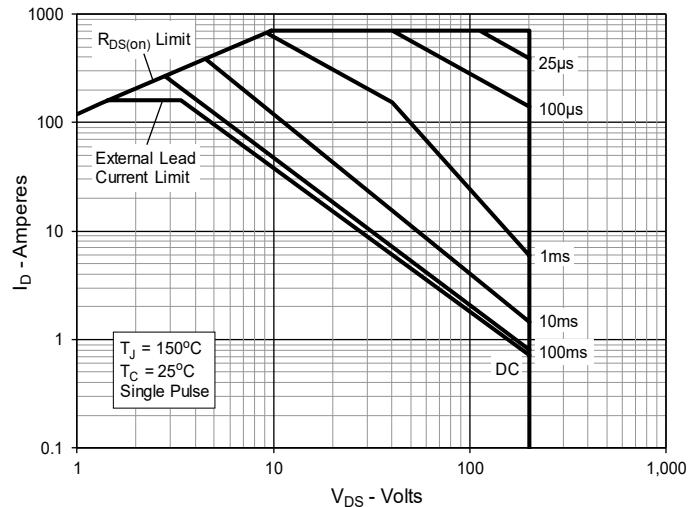
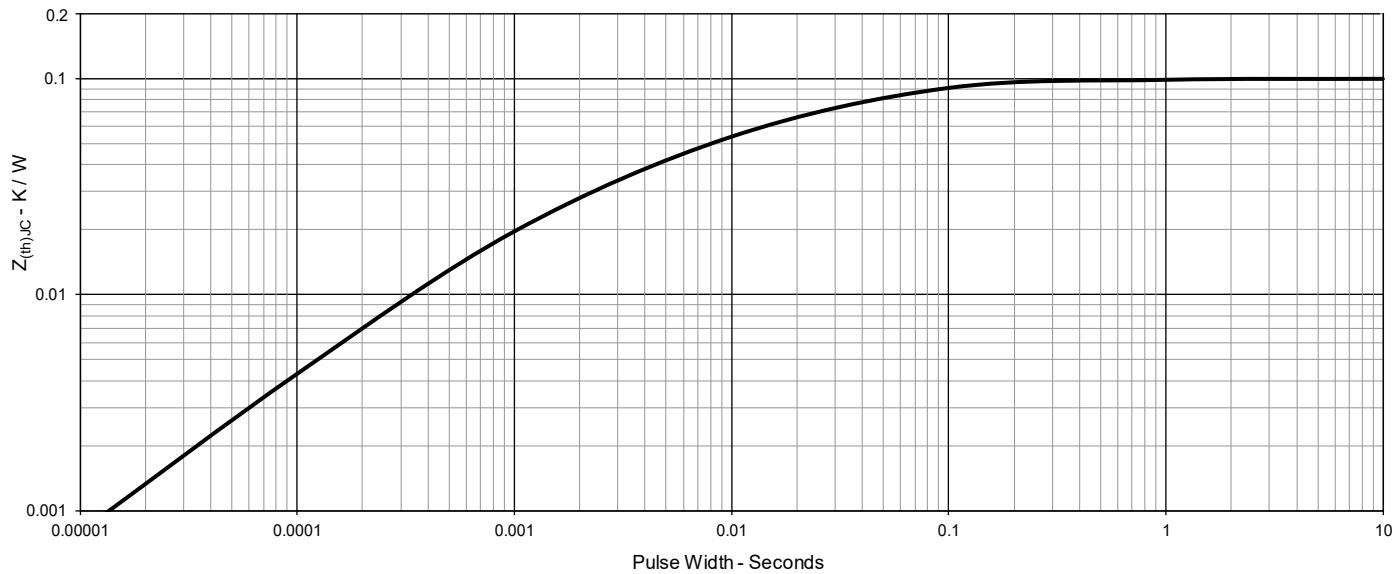
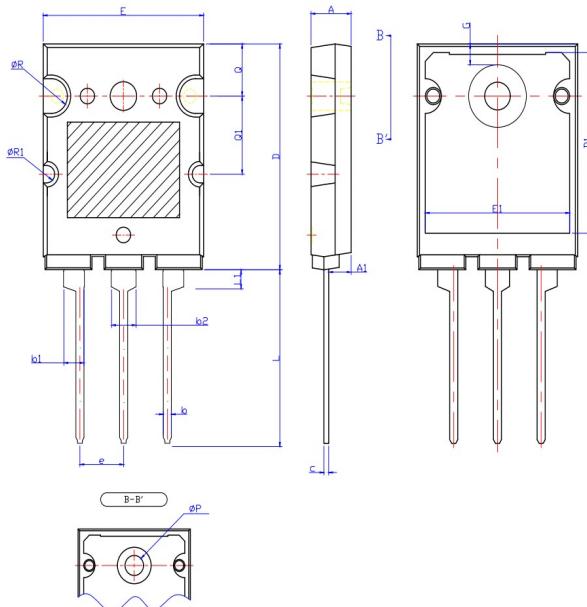


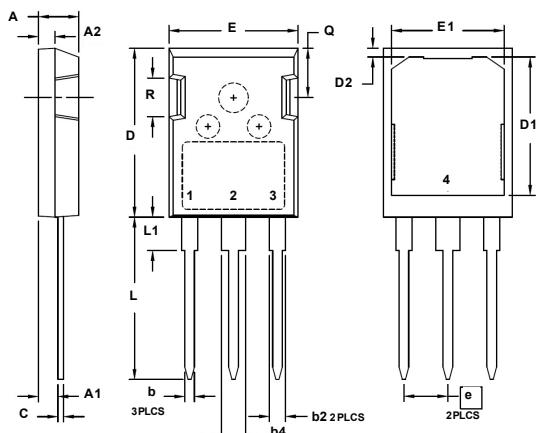
Fig. 15. Maximum Transient Thermal Impedance



TO-264K Outline


1 - Gate
2,4 - Drain
3 - Source

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.189	0.205	4.80	5.20
A1	0.098	0.122	2.50	3.10
b	0.035	0.049	0.90	1.25
b1	0.091	0.106	2.30	2.70
b2	0.110	0.126	2.80	3.20
c	0.020	0.033	0.50	0.85
D	1.016	1.031	25.80	26.20
E	0.780	0.795	19.80	20.20
e	0.203	0.226	5.15	5.75
L	0.768	0.807	19.50	20.50
L1	0.094	0.102	2.40	2.60
ØP	0.118	0.134	3.00	3.40
Q	0.228	0.244	5.80	6.20
Q1	0.346	0.362	8.80	9.20
E1	0.701	0.717	17.80	18.20
D1	0.811	0.827	20.60	21.00
G	0.087	0.102	2.20	2.60
ØR		0.079		2.00
ØR1		0.039		1.00

PLUS247™ Outline


1 - Gate
2,4 - Drain
3 - Source

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b2	.075	.087	1.91	2.20
b4	.115	.126	2.92	3.20
C	.024	.031	0.61	0.80
D	.819	.840	20.80	21.34
D1	.650	.690	16.51	17.53
D2	.035	.050	0.89	1.27
E	.620	.635	15.75	16.13
E1	.520	.560	13.08	14.22
e	.215 BSC		5.45 BSC	
L	.780	.810	19.81	20.57
L1	.150	.170	3.81	4.32
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83



IXFK300N20X3

IXFX300N20X3



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